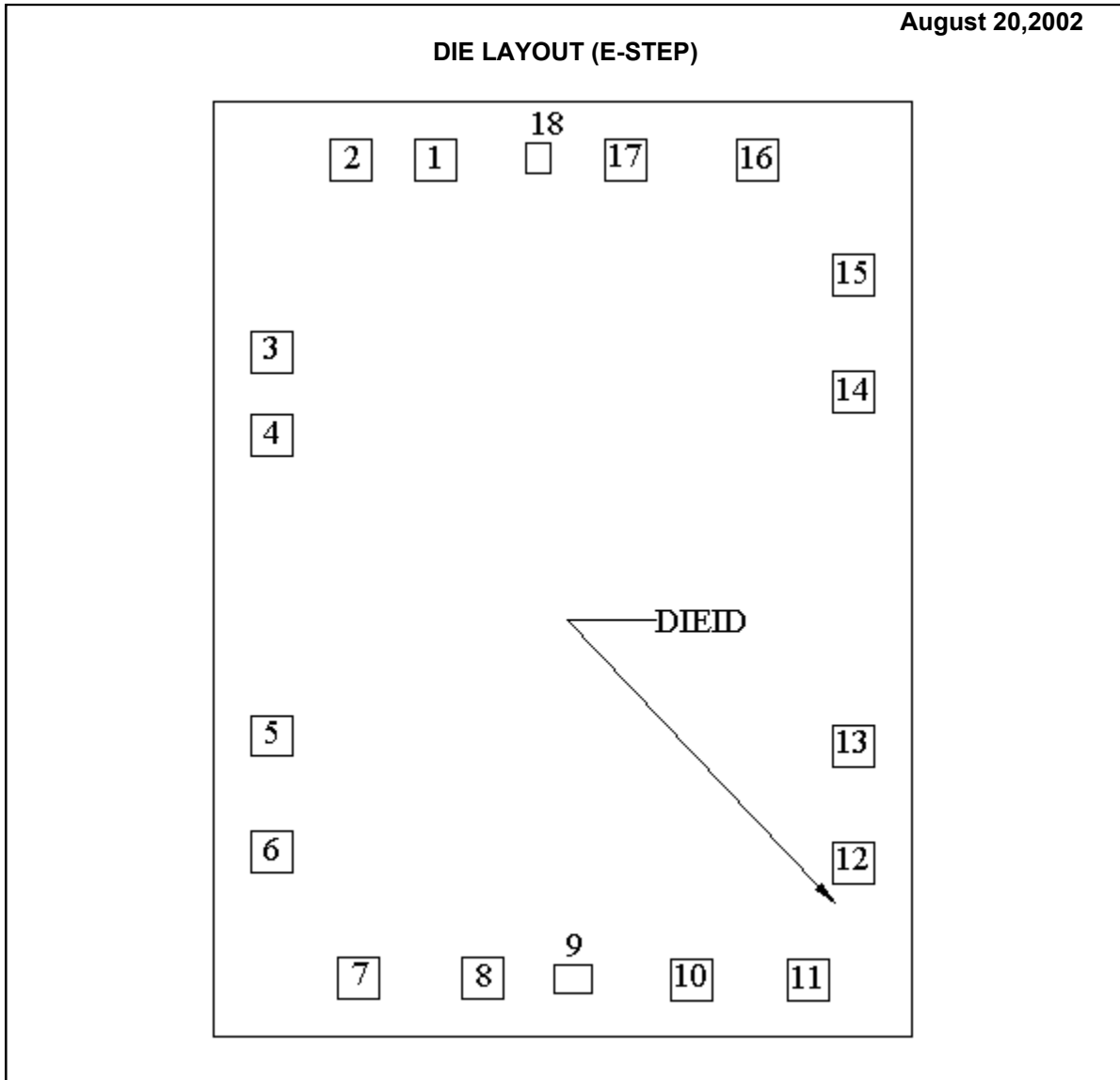


**LM3524D MDC MWC**  
**REGULATING PULSE WIDTH MODULATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1524E	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	E	Bond Pad Metalization	ALUMINUM
<b>Physical Attributes</b>		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1524µm x 2032µm 60mils x 80mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	182µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (E-Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INV INPUT	1	-279	889	90	x	90
NI INPUT	2	-461	889	90	x	90
OSC OUTPUT	3	-635	473	90	x	90
CL SENSE +	4	-635	291	90	x	90
CL SENSE -	5	-636	-363	89	x	90
RT	6	-635	-616	90	x	90
CT	7	-444	-889	90	x	90
GND	8	-174	-890	90	x	90
NC	9	23	-891	82	x	61
COMPENSATION	10	281	-893	90	x	90
SHUTDOWN	11	534	-895	90	x	90
EMITTER A	12	635	-639	90	x	90
COLLECTOR A	13	635	-384	90	x	90
COLLECTOR B	14	635	384	90	x	90
EMITTER B	15	635	639	90	x	90
VIN	16	425	889	90	x	90
VREF	17	137	892	90	x	90
NC	18	-55	895	54	x	66

**LM3524D MDC MWC**  
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